

HiDura™ D1MG33J BK0816

polyamide 612



HiDura D1MG33J BK0816 is an organically heat stabilized, 33% glass filled PA612 designed for injection molding applications.

General

Regional Availability	• North America	• Europe	• Asia Pacific
Additive	• Heat Stabilizer		
Features	• Chemical Resistant	• Organic Heat Stabilized	• Thermal Stability
Appearance	• Black		
Forms	• Pellets		
Processing Method	• Injection Molding		

Physical

	dry	cond.	Unit	Test Standard
Density	1.32	-	g/cm ³	ISO 1183
Molding Shrinkage				ISO 294-4
Across Flow : 23°C, 2.00 mm	1.3	*	%	
Flow : 23°C, 2.00 mm	0.4	*	%	
Water Absorption				ISO 62
23°C, 24 hr	0.3	*	%	
Equilibrium, 23°C, 50% RH	0.8	*	%	

Mechanical

	dry	cond.	Unit	Test Standard
Tensile Modulus (23°C)	9800	7900	MPa	ISO 527-2
Tensile Stress (Break, 23°C)	160	127	MPa	ISO 527-2
Tensile Strain (Break, 23°C)	3.5	5	%	ISO 527-2
Flexural Modulus (23°C)	9400	7800	MPa	ISO 178
Flexural Strength (23°C)	235	177	MPa	ISO 178

Impact

	dry	cond.	Unit	Test Standard
Charpy Notched Impact Strength				ISO 179/1eA
+23°C	13	14	kJ/m ²	
-30°C	10	10	kJ/m ²	
-40°C	10	10	kJ/m ²	
Charpy Unnotched Impact Strength				ISO 179/1eU
+23°C	84	77	kJ/m ²	
-30°C	69	70	kJ/m ²	
-40°C	69	65	kJ/m ²	
Notched Izod Impact Strength				ISO 180/1A
+23°C	12	13	kJ/m ²	

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-30°C	10	9.8	kJ/m²
-40°C	10	9.3	kJ/m²

Thermal	dry	cond.	Unit	Test Standard
Heat Deflection Temperature				ISO 75-2/A
1.80 MPa, Unannealed	197	191	°C	
0.45 MPa, Unannealed	211	210	°C	
Melting Temperature	218	*	°C	ISO 11357-3

Electrical	dry	cond.	Unit	Test Standard
Dielectric Strength (1.00 mm)	31	30	kV/mm	IEC 60243

Injection	Value	Unit
Drying Temperature	≤ 80	°C
Drying Time	≤ 4	h
Processing (Melt) Temperature	240 - 300	°C
Mold Temperature	60 - 120	°C

HiDURA™